

ACP 2019

Asia Communications and Photonics Conference

Nov. 2-5, 2019 | Chengdu, China



Asia Communications and Photonics Conference (ACP 2019) Sponsor Invitation

Asia Communications and Photonics Conference (ACP) is now the largest conference in the Asia-Pacific region on optical communication, photonics and relevant technologies. ACP has been held annually tracing back to 2001 and jointly sponsored by OSA, SPIE, IEEE Photonics Society. The conference attracts 600-1000 delegates every year.

ACP 2019 will be held by Southwest Jiaotong University and University of Electronic Science and Technology of China in **InterContinental Chengdu Global Center, Chengdu, on November 2-5, 2019**. We would like to invite you to participate in this wonderful meeting, to share your most significant advances, and to take the chance of interacting in a mutually profitable relationship.

Honorary Chairs

Bingkun Zhou, Tsinghua University, China

Alan E. Willner, University of Southern California, USA

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Hosts

Southwest Jiaotong University

University of Electronic Science and Technology of China

Co-Hosts:

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Light: science & applications

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Subcommittee

Sc 1: Optical Fibers, Fiber-based Devices and Sensors

Sc 2: Optical Transmission Sub-systems, Systems and Technology

Sc 3: Network Architectures, Management and Applications

Sc 4: Photonic Components and Integration

Sc 5: Microwave Photonics and Fiber Wireless Convergence

Sc 6: Micro-, Nano-, and Quantum Photonics: Science and Applications

Exhibition and sponsorships

| Items | Diamond | Platinum | Gold | Sliver | Bronze |
|--|-----------------|-----------------|-----------------|--------------|--------------|
| Included in co-hosts | √ | | | | |
| Included in special thanks | | √ | | | |
| Back cover ad | √ | | | | |
| Name the reception | Choose 1 | | | | |
| Free place for workshop (half day) | | | | | |
| Gift sponsor | Choose 1 | | | | |
| Name the best student paper award | | | | | |
| Inside Front Cover Ad (colored, full page) | | Choose 1 | | | |
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| Material bags Ad (1 side) | | | | | |
| Name the coffee break (Only 4) | | | Choose 1 | | |
| Display stand (2*4 m, only 5 places) | √ | | | | |
| Wechat special promotion | √ | | | | |
| A4 leaflet/trifold in material bag | | √ | √ | √ | |
| Free attendees | 5 | 4 | 3 | 2 | 1 |
| Free award banquet tickets | 5 | 4 | 3 | 2 | 1 |
| Table (1.8*0.4m) | 2 | 2 | 2 | 1 | 1 |
| Inside page Ad (full page) | | | √ | √ | |
| Link & logo in | √ | √ | √ | √ | √ |
| Total fee | 150000 | 100000 | 60000 | 40000 | 20000 |
| | RMB | RMB | RMB | RMB | RMB |

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Conference website: <http://www.acpconf.org>